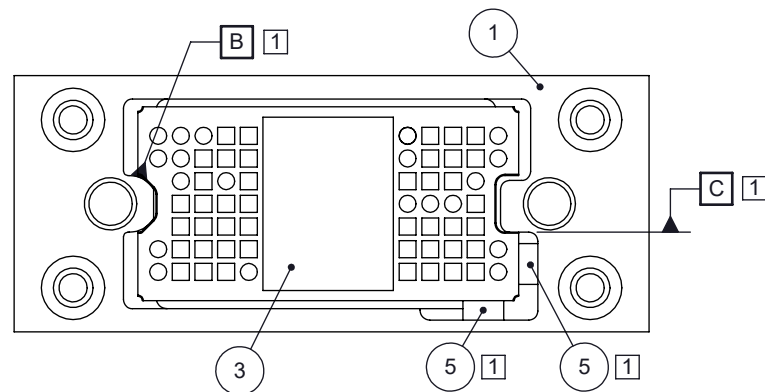
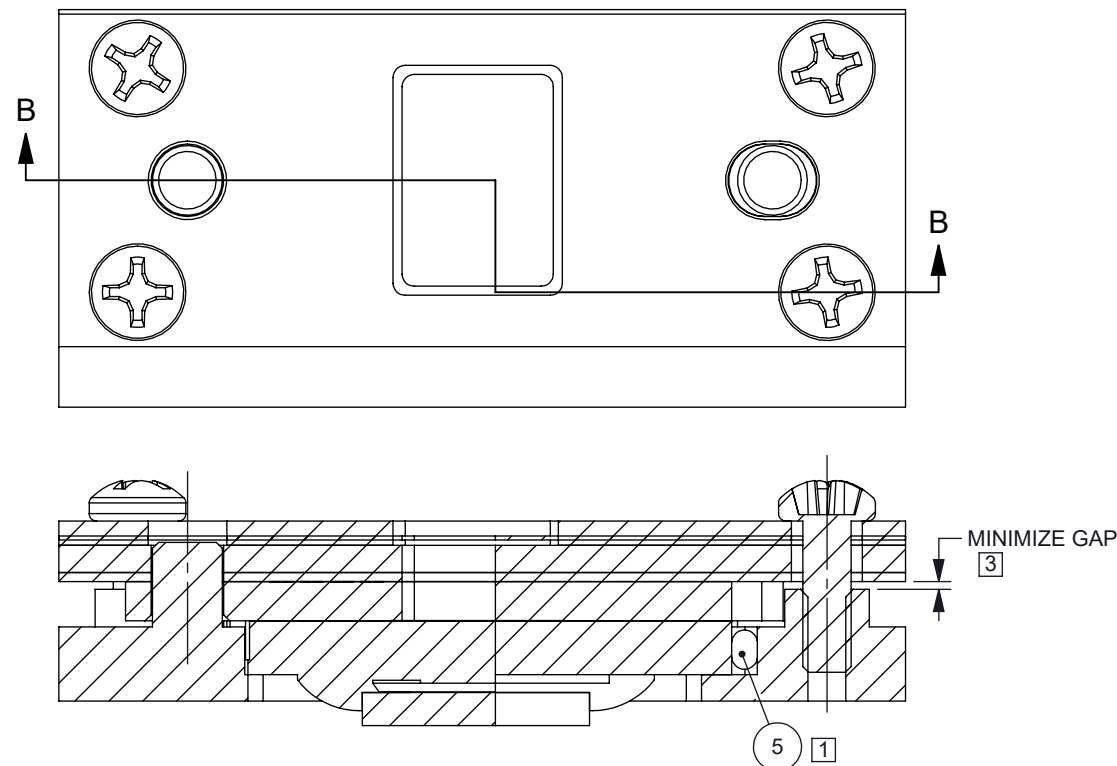


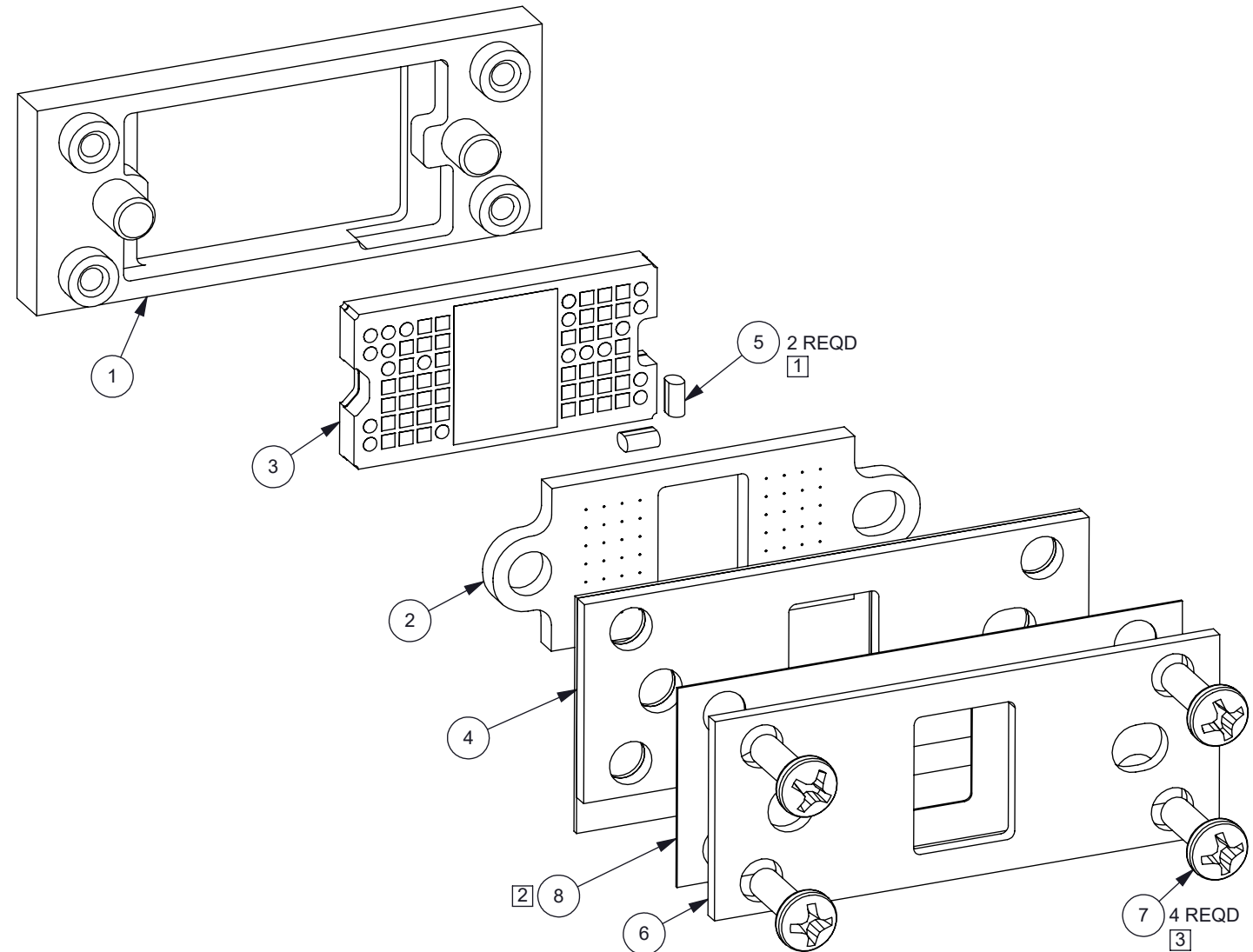
3] WHEN TIGHTENING SCREWS (ITEM 7) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AND ELECTRICAL INTERFACE AREAS SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORMLY DISTRIBUTED LOAD ACROSS THE AREAS. MOUNTING LOADS APPLIED TO THE DMD SHOULD BE UNIFORMLY DISTRIBUTED. TO HELP ENSURE UNIFORM LOADING OF THE DMD. THE GAP BETWEEN THE 4 BOSSES ON THE INTERFACE (ITEM 1) AND THE PCB (ITEM 4) SHOULD BE MINIMIZED TO HELP PREVENT BENDING AND NON UNIFORM LOADS ON THE DMD. THIS IS ACHIEVED BY CONTROL OF THE NOMINAL DIMENSIONS AND TOLERANCES OF ALL PARTS THAT CONTRIBUTE TO THE GAP. THE USE OF AN ASSEMBLY FIXTURE AND/OR PROCEDURE THAT INCORPORATES MULTIPLE TIMES OF PARTIAL TIGHTENING OF THE SCREWS BEFORE FINAL TORQUE IS BENEFICIAL.




VIEW A - DMD ALIGNMENT TO INTERFACE (OPTICAL CHASSIS)



SECTION B-B



1	8	2516677	INSULATOR, PCB, SERIES 247	
4	7		SCREW, PAN HEAD M1.6 X 5M LENGTH	
1	6	2516675	CLAMP, FLEX, SERIES 247	
2	5	2512939	SHIM, FOAM ALIGNMENT (ELASTOMERIC WEDGE)	
1	4	2516676	PCB FLEX ASSEMBLY OUTLINE, SERIES 247	
1	3		DMD, SERIES 249	
1	2	2516672	INTERPOSER, 56 CONTACT	
1	1	2518081	INTERFACE, SERIES 249 MOUNTING	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

		UNLESS OTHERWISE SPECIFIED <ul style="list-style-type: none">● DIMENSIONS ARE IN MILLIMETERS● TOLERANCES: ANGLES ±1°<div>2 PLACE DECIMALS ±0.25</div><div>1 PLACE DECIMALS ±0.50</div>● DIMENSIONAL LIMITS APPLY BEFORE PROCESSES● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994● REMOVE ALL BURRS AND SHARP EDGES● PARENTHETICAL INFO FOR REF ONLY	DWN J. McKINLEY	DATE 10/11/2021	<div> TEXAS INSTRUMENTS</div> <div>ASSEMBLY, SERIES 249 MOUNTING CONCEPT</div>		
			Engr				
			CQE/QA				
			CM				
NONE	0314RD				SIZE B	DWG NO 2518079	REV A
NEXT ASSY	USED ON						
APPLICATION			Apprvd		SCALE 1:1		SHEET 1 OF 2

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SSZZ031 January 01, 2013



DWN	DATE
J. McKINLEY	10/11/2021

DATE
10/11/2021

1	SIZE B
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DRAWING NO	2518079-Assv-s249
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REV
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SCALE 2:1

SHEET 2 OF 2